

### **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) An apparatus, comprising:  
an adhesion layer abutting a conductive pad;  
a molybdenum-containing barrier layer abutting said adhesion layer;  
a wetting layer abutting said molybdenum-containing barrier layer; and  
high tin content solder material abutting said wetting layer.
2. (Original) The apparatus of claim 1, wherein said molybdenum-containing barrier layer comprises a material containing at least about 90% (atomic) molybdenum.
3. (Original) The apparatus of claim 1, wherein said high tin content solder material comprises a material containing at least about 90% (by weight) tin.
4. (Original) The apparatus of claim 1, further comprising said conductive pad abutting at least one layer of low k dielectric material.
5. (Original) The apparatus of claim 4, wherein said at least one layer of low-k dielectric material comprises at least one layer of carbon doped oxide.

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6. (Original) The apparatus of claim 1, wherein said wetting layer is substantially subsumed in said high tin content solder material forming an intermetallic compound layer.

7.-20. (Canceled)